



Ed: 00, Date: 26 April 2006

International Rectifier Road Map to provide Lead Free Products to meet the ROHS Directive passed by European Legislation in Dec 2002 to ban the use of Pb, Hg, Cd, Cr VI, PBB, PBDE in Electrical and Electronic Equipment. These Directive Affects all the Products Sold after July 2006. Exception: Telecom equipment till 2010.

High Lead Solder application (>85% LEAD ALLOY)

International Rectifier is dedicated to provide high power Products manufactured with Lead – Free finish on all the external Terminals and/or the device bases in order to comply with ROHS Directive before the legislative deadlines.

In this section, we would like to highlight that presently "Lead-Free" is restricted to the device external terminals and / or bases, Where as die attach solder inside the package are still having high lead content which is exempted from ROHS Directives.

Package	Earliest Conversion Date	Latest Conversion Date	PbF / RoHS
PUK	October 2005	June 2006	PbF
A-E, BKR and G Puk			
Compressed Module IAP, MAP and SMAP	October 2005	June 2006	PbF
Compressed Stud SCR-TO93/TO94/TO118	October 2005	June 2006	PbF
Modules Pace-Pak and T-Module	October 2005	June 2006	RoHS
Bridges GBPC, MB, MT	October 2005	June 2006	RoHS
Bridges KBPC6/ KBPC8	October 2005	June 2006	PbF
Low Power Bridges 1KABE, 2KBB/ 2KBBR, 2KBP, KBPC1,	October 2005	June 2006	RoHS
Pressfit 8AF	October 2005	June 2006	RoHS
Medium Power Discrete Diode DO4, DO5, Plastic Do5	October 2005	June 2006	RoHS
Medium Power Discrete SCR TO-48 / TO-65	October 2005	June 2006	RoHS
High Power Discrete Diode Alloy DO8/ DO9, Brazed DO8/DO9	October 2005	June 2006	RoHS
High Power Discrete SCR TO-93/ TO-94	October 2005	June 2006	RoHS

Conversion of Lead Free Parts: High Power Products

Contact High Power Product Marketing for any other Packages than mentioned above. (IR – HPG)  $\,$ 





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- 1. Hockey Puks, Compressed Modules and Compressed Stud are 100% Lead Free (PbF)
- 2. All other Products still Contain Lead Content inside the package, as high melting point solder with more than 85% lead . This is exempted from RoHS Directives.
- 3. There is no obsolescence of any Product due to " Lead- Free" Conversion.
- 4. External Finishing of most of the product is either Nickel or Tin
- 5. For Traceability and identification of Devices for RoHS / PbF, Devices are marked with either "PbF" or "P" for the products where changes has been implemented
- 6. All other Part Numbers will remain Unchanged as they are in Compliance with RoHS directives.